

HGTP20N35G3VL, HGT1S20N35G3VL, HGT1S20N35G3VLS

December 2001

20A, 350V N-Channel, Logic Level, Voltage Clamping IGBTs



- Logic Level Gate Drive
- Internal Voltage Clamp
- ESD Gate Protection
- T_J = 175°C
- Ignition Energy Capable

Description

This N-Channel IGBT is a MOS gated, logic level device which is intended to be used as an ignition coil driver in automotive ignition circuits. Unique features include an active voltage clamp between the collector and the gate which provides Self Clamped Inductive Switching (SCIS) capability in ignition circuits. Internal diodes provide ESD protection for the logic level gate. Both a series resistor and a shunt resistor are provided in the gate circuit.

	AVAILABILITY	
PACKAGING		

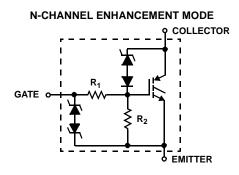
PART NUMBER	PACKAGE	BRAND
HGTP20N35G3VL	T0-220AB	20N35GVL
HGT1S20N35G3VL	T0-262AA	20N35GVL
HGT1S20N35G3VLS	T0-263AB	20N35GVL

NOTE: When ordering, use the entire part number. Add the suffix 9A to obtain the TO-263AB variant in the tape and reel, i.e., HGT1S20N35G3VLS9A.

The development type number for this device is TA49076.

Packages JEDEC TO-220AB EMITTER COLLECTOR GATE COLLECTOR (FLANGE) JEDEC TO-262AA EMITTER COLLECTOR GATE COLLECTOR (FLANGE) JEDEC TO-263AB COLLECTOR (FLANGE) GATE EMITTER

Terminal Diagram



HGTP20N35G3VL

Absolute Maximum Ratings T_C = +25°C, Unless Otherwise Specified

	HGT1S20N35G3VL HGT1S20N35G3VLS	UNITS
Collector-Emitter Bkdn Voltage At 10mA, R _{GE} = 1kΩ BV _{CER}	375	V
Emitter-Collector Bkdn Voltage At 10mA BV _{ECS}	24	V
Collector Current Continuous At $V_{GE} = 5.0V$, $T_C = +25^{\circ}C$, Figure 7 I_{C25}	20	Α
At $V_{GE} = 5.0V$, $T_C = +100^{\circ}C$ I_{C100}	20	Α
Gate-Emitter-Voltage (Note)V _{GES}	±10	V
Inductive Switching Current At L = 2.3mH, T _C = +25° CI _{SCIS}	26	А
At L = 2.3mH, T $_{C}$ = +175°C I _{SCIS}	18	Α
Collector to Emitter Avalanche Energy At L = 2.3mH, $T_C = +25^{\circ}C$ E_{AS}	775	mJ
Power Dissipation Total At $T_{C} = +25^{\circ}CP_{D}$	150	W
Power Dissipation Derating T _C > +25°C	1.0	W/°C
Operating and Storage Junction Temperature Range	-40 to +175	°C
Maximum Lead Temperature for SolderingTL	260	°C
Electrostatic Voltage at 100pF, 1500Ω ESD	6	KV
NOTE: May be exceeded if I _{GEM} is limited to 10mA.		

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HGTP20N35G3VL, HGT1S20N35G3VL, HGT1S20N35G3VLS Rev. B

Electrical Specifications $T_{C} = +25^{\circ}C$, Unless Otherwise Specified

					LIMITS			
PARAMETERS	SYMBOL	TEST CONDITIONS		MIN	ТҮР	MAX	UNITS	
Collector-Emitter Breakdown Voltage	BV _{CES}	$I_{\rm C} = 10 {\rm mA},$	T _C = +175°C	310	345	380	V	
		$V_{GE} = 0V$	T _C = +25°C	320	350	380	V	
			$T_{\rm C} = -40^{\rm o}{\rm C}$	320	355	390	V	
Collector-Emitter Breakdown Voltage	BV _{CER}	$I_{C} = 10mA$ $V_{GE} = 0V$ $R_{GE} = 1k\Omega$	T _C = +175°C	300	340	375	V	
			T _C = +25°C	315	345	375	V	
			$T_{\rm C} = -40^{\rm o}{\rm C}$	315	350	390	V	
Gate-Emitter Plateau Voltage	V _{GEP}	I _C = 10A V _{CE} = 12V	T _C = +25 ^o C	-	3.7	-	V	
Gate Charge	Q _{G(ON)}	$I_C = 10A$ $V_{GE} = 5V$ $V_{CE} = 12V$	T _C = +25°C	-	28.7	-	nC	
Collector-Emitter Clamp Bkdn. Voltage	BV _{CE(CL)}	$I_{\rm C} = 10 {\rm A}$ ${\rm R}_{\rm G} = 0 {\rm \Omega}$	T _C = +175°C	325	360	395	V	
Emitter-Collector Breakdown Voltage	BV _{ECS}	I _C = 10mA	T _C = +25°C	20	32	-	V	
Collector-Emitter Leakage Current	I _{CES}	V _{CE} = 250V	T _C = +25°C	-	-	5	μΑ	
		V _{CE} = 250V	T _C = +175 ^o C	-	-	250	μA	
Collector-Emitter Saturation Voltage V _{CE(S}	V _{CE(SAT)}	$V_{CE(SAT)}$ $I_{C} = 10A$ $V_{GE} = 4.5V$ $I_{C} = 20A$ $V_{GE} = 5.0V$	T _C = +25°C	-	1.3	1.6	V	
			T _C = +175°C	-	1.25	1.5	V	
			T _C = +25°C	-	1.6	2.8	V	
			T _C = +175°C	-	1.9	3.5	V	
Gate-Emitter Threshold Voltage	V _{GE(TH)}	$I_{C} = 1mA$ $V_{CE} = V_{GE}$	T _C = +25°C	1.3	1.8	2.3	V	
Gate Series Resistance	R ₁		T _C = +25°C	-	1.0	-	kΩ	
Gate-Emitter Resistance	R ₂		T _C = +25°C	10	17	25	kΩ	
Gate-Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 10V$		±400	±590	±1000	μA	
Gate-Emitter Breakdown Voltage	BV _{GES}	$I_{GES} = \pm 2mA$		±12	±14	-	V	
Current Turn-Off Time-Inductive Load	^t D(OFF)I + ^t F(OFF)I	$\begin{split} I_{C} &= 10A, \ R_{G} = 25\Omega, \\ L &= 550 \mu H, \ R_{L} = 26.4\Omega, \ V_{GE} = 5V, \\ V_{CL} &= 300V, \ T_{C} = +175^{o}C \end{split}$		-	15	30	μs	
Inductive Use Test	nductive Use Test	L = 2.3 mH,	T _C = +175°C	18	-	-	A	
		$V_G = 5V,$ $R_G = 0\Omega$	$T_{\rm C} = +25^{\rm o}{\rm C}$	26	-	-	Α	
Thermal Resistance	$R_{\theta JC}$		-	-	-	1.0	°C/W	

Typical Performance Curves

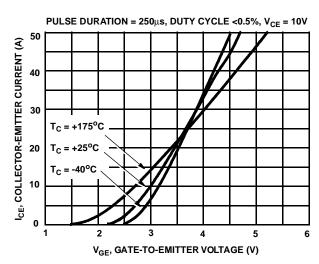


FIGURE 1. TRANSFER CHARACTERISTICS

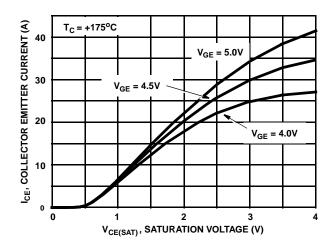


FIGURE 3. COLLECTOR-EMITTER CURRENT AS A FUNCTION OF SATURATION VOLTAGE

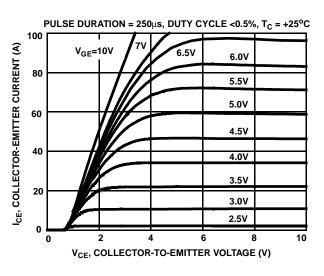


FIGURE 2. SATURATION CHARACTERISTICS

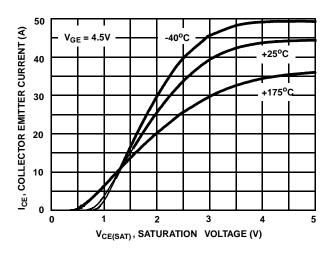
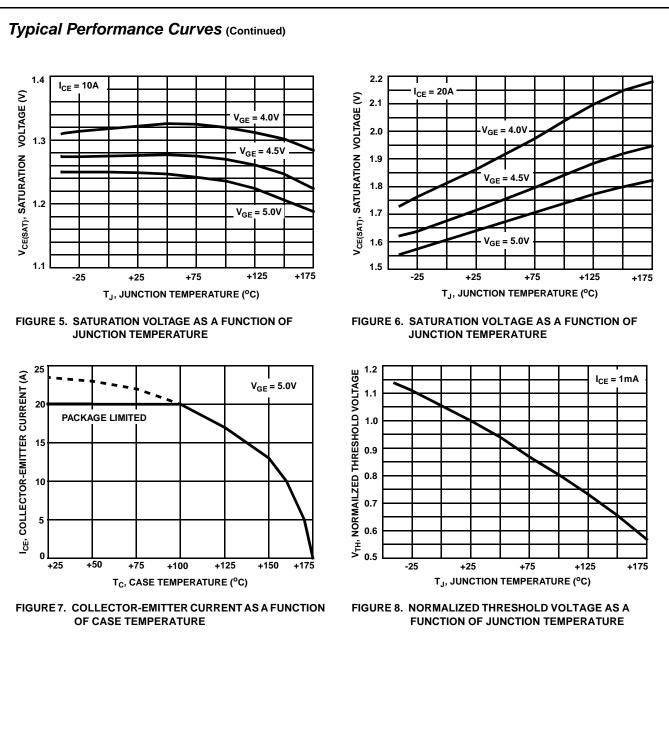
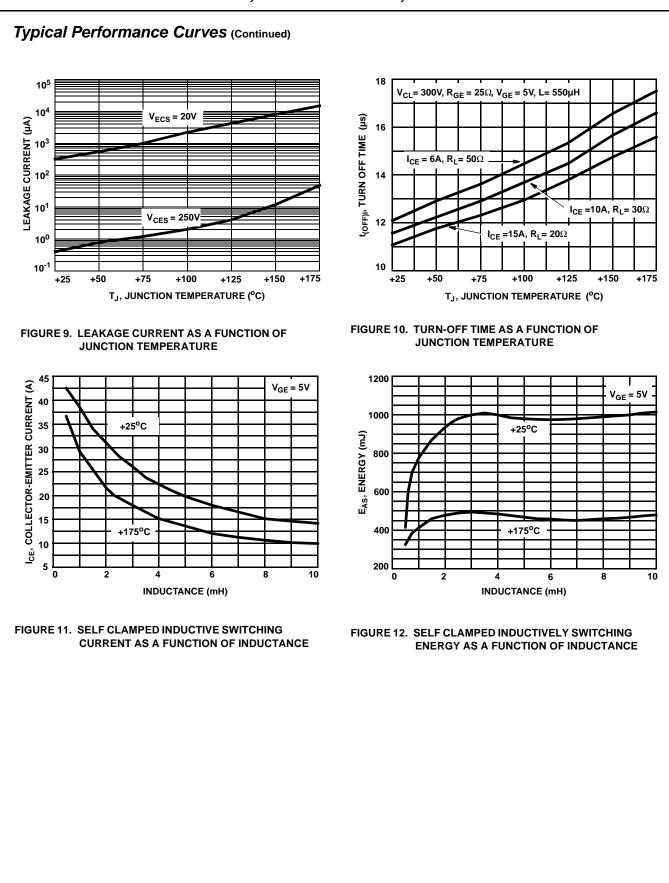
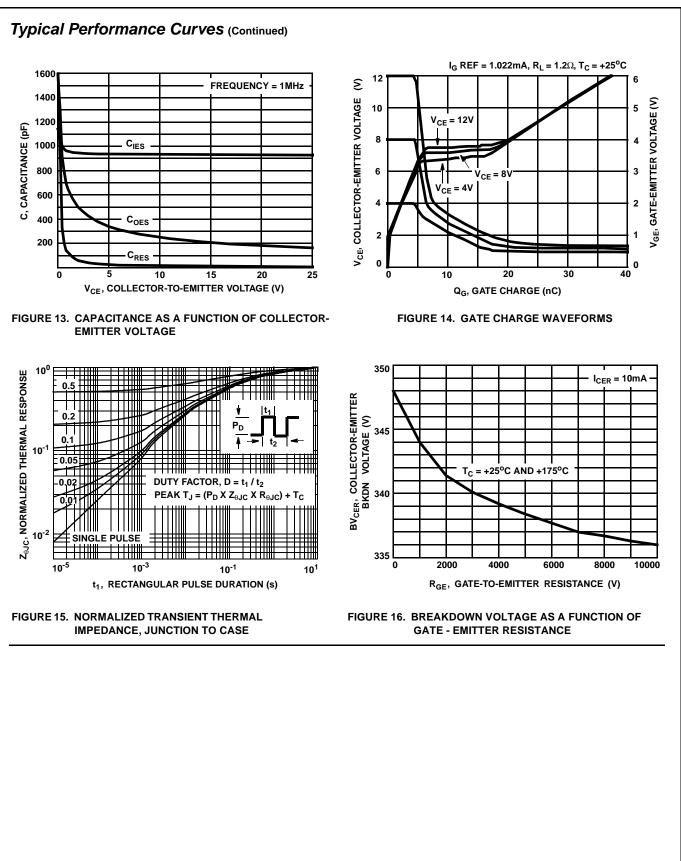


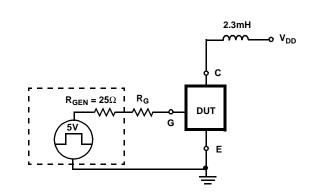
FIGURE 4. COLLECTOR-EMITTER CURRENT AS A FUNCTION OF SATURATION VOLTAGE







Test Circuits



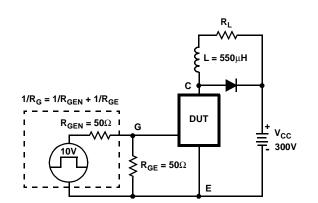


FIGURE 17. USE TEST CIRCUIT

FIGURE 18. INDUCTIVE SWITCHING TEST CIRCUIT

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